In the Claims:

1. (Currently amended) An electronic device (1)

- with a base plate (2),

- with an electronics housing (3) which is connected to the base plate (2), with at least one bond contact ~~bearer~~ terminal (5),

~~characterised~~ characterized in that the bond contact ~~bearer (5)~~ terminal has a bond contact area adapted to establish an electrical bond connection, and the bond contact terminal is supported on the base plate (2) by a supporting body (6) in such a manner that the supporting body (6) exerts a pretension force onto the bond contact ~~bearer (5).~~ terminal, and the supporting body is arranged and positioned so that the bond contact area of the bond contact terminal is located in an area of the supporting body projected in a direction in which the supporting body exerts the pretension force onto the bond contact terminal.

2. (Currently amended) An electronic device according to claim 1, ~~characterised~~ characterized in that a projection height of the supporting body (6) above the base plate (2) is greater than [[~~the~~]] a distance between the bond contact ~~bearer~~ terminal (5) and the base plate (2) in a pre-assembly condition without yet having the pretension force exerted by the supporting body onto the bond contact terminal.

Claims 3 and 4 (Canceled).

5. (Withdrawn - currently amended) A procedure for bonding the electronic device (1) according to claim 1, comprising the steps:

providing the base plate (2),

connecting the electronics housing (3) via the supporting body (6) with the base plate (2) in such a manner that the supporting body (6) exerts the pretension force onto the bond contact ~~bearer~~ terminal (5), and

creating [[a]] the electrical bond connection between the bond contact ~~bearer~~ terminal (5) of the electronics housing (3) and an additional bond contact ~~bearer.~~ terminal of an additional electronic component.

6. (Previously presented) An electronic device according to claim 1, characterized in that the supporting body (6) represents a separate component from the base plate (2), which is mechanically connected to the electronics housing (3).

7. (Previously presented) An electronic device according to claim 1, characterized in that the supporting body (6) is designed as a projecting ring or as a plurality of projecting individual segments.

8. (Currently amended) An electronic device comprising:

a base plate;

an electronics housing connected to said base plate;

an electrical bonding contact terminal that protrudes from said housing, ~~and that~~ wherein said bonding contact terminal has a free terminal end ~~projecting~~ that projects away from said housing and that includes a bond contact area adapted to establish an electrical bond connection, and wherein said bonding contact terminal further has a root end adjoining said housing opposite said free terminal end; and

a support body that is interposed between said free terminal end including said bond contact area of said bonding contact terminal and said base plate, and that supports said free terminal end of said bonding contact terminal relative to said base plate, and that deflects said free terminal end of said bonding contact terminal away from said base plate and thereby exerts a pre-stressing force onto said bonding contact terminal because a projection height of said support body from said base plate is greater than a nominal distance between said [[~~root~~]] free terminal end of said bonding contact terminal and said base plate in a pre-assembly condition without said support body yet interposed therebetween; and

wherein said support body is arranged and positioned so that said bond contact area of said bonding contact terminal is located in an area of said support body

projected in a direction in which said support body exerts said pre-stressing force onto said bonding contact terminal.

Claim 9 (Canceled).

10. (Currently amended) The electronic device according to claim 8, further comprising an electronic component having a second bonding contact terminal, which is electrically bonded to said bond contact area of said bonding contact terminal that protrudes from said housing.

11. (Previously presented) The electronic device according to claim 8, wherein said support body is a discrete component separate from said base plate and is mechanically connected to said electronics housing and merely resting on said base plate.

12. (Previously presented) The electronic device according to claim 8, wherein said support body is a support frame with a ring shape extending continuously along a perimeter of an opening of said housing.

13. (New) An electronic device according to claim 1, wherein the bond contact area is provided on a terminal end portion directly adjoining a free terminal end of the bond contact terminal, and the terminal end portion including the bond

contact area is positioned and supported on the supporting body, and the free terminal end of the bond contact terminal does not project beyond the supporting body.

14. (New) An electronic device according to claim 1, expressly omitting any electrical connection of the bond contact terminal to an additional electronic component at a location away from the supporting body.

15. (New) An electronic device according to claim 1, wherein the supporting body supports the bond contact terminal so as to prevent a vibrating deflection of the bond contact terminal at the bond contact area.

16. (New) An electronic device according to claim 1, wherein said supporting body contacts a surface of said bond contact terminal directly opposite said bond contact area at a location directly opposite said bond contact area.

17. (New) The electronic device according to claim 8, wherein said free terminal end of said bonding contact terminal does not project beyond said support body.

18. (New) The electronic device according to claim 8, expressly omitting any electrical connection of said bonding contact terminal to an additional electronic component at a location away from said support body.

19. (New) The electronic device according to claim 8, wherein said support body supports said bonding contact terminal so as to prevent a vibrating deflection of said bonding contact terminal at said bond contact area.

20. (New) The electronic device according to claim 8, wherein said support body contacts a surface of said bonding contact terminal directly opposite said bond contact area at a location directly opposite said bond contact area.

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